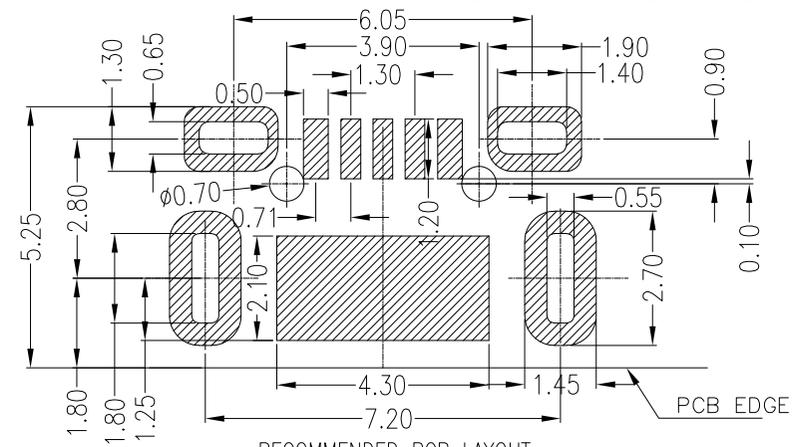
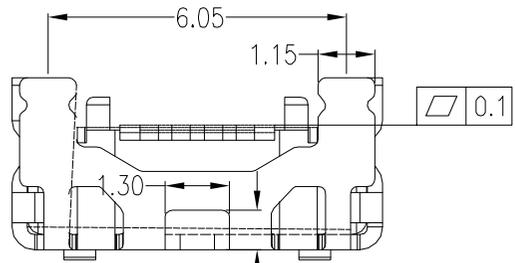


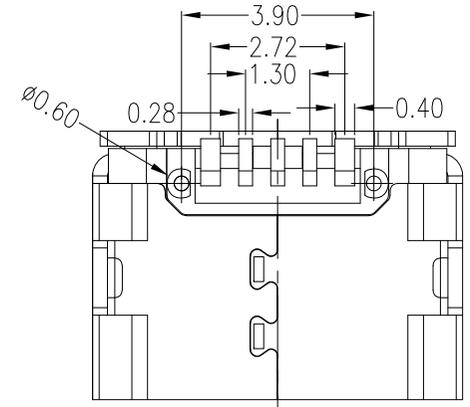
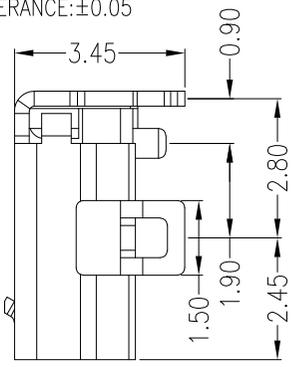
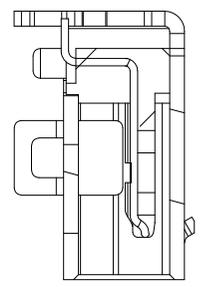
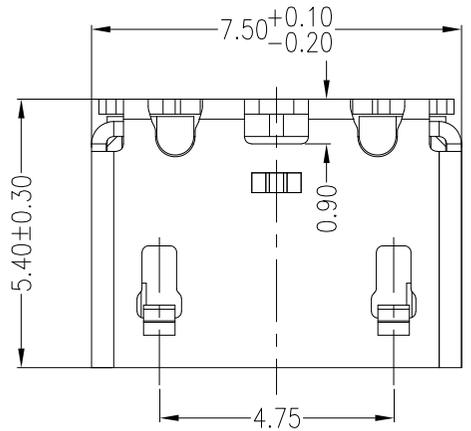
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2019/06/27	Phebe Su
A1			Change	2020/07/13	Ken Lin

Note:
 1.Material:
 1.1 Housing: LCP BLACK, UL94V-0
 1.2 Contact: C7025
 1.3 Shell: SUS
 2.FINISH:
 Contact: Au 1.0~1.15u" Plated on Contact Area,
 Nickel 40~100u" Plated Underplating Over All.
 Shell: Sn 50~110u" Plated Underplating Over All.
 Nickel 40~100u" Plated Underplating Over All.
 3.Specification:
 2.1 Current rating: 1,5PIN 3A Max/2,3,4PIN 1A
 2.2 Rated voltage: 30VAC
 2.3 Dielectric withstanding voltage: 100 V(ac) for 1 min.
 2.4 Contact resistance: 30 mΩ Max.
 2.5 Insulation resistance: 100 MΩ Min.
 2.6 Total mating force: 3.57 Kgf Max.
 2.7 Total unmating force: 1.0 Kgf Min.
 2.8 Temperature range: -40°C~85°C

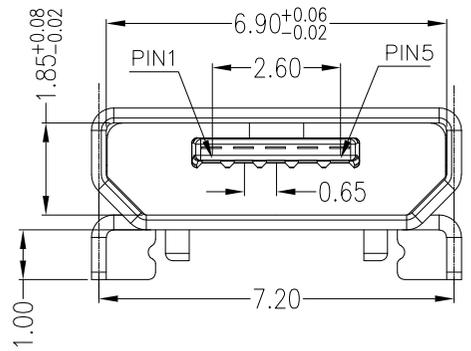


RECOMMENDED PCB LAYOUT
 TOLERANCE: ±0.05



MATRIX PART NO:
MUSB 05 - 01 - 357

Matrix-USB Pin number Gold Plating: 01=1u" Series Number



PIN NO.	SLGNL NAME	Matrix Electronics Co.,Ltd			
PIN 1	V BUS	TOLERANCE: X:X ±0.15 X:XX ±0.10 X:XXX ±0.05 ANGLE: ±3° UNIT: mm [inch] SCALE:1:1 SIZE:A4	DESIGN BY :	DATE :	PART NAME:
PIN 2	D-		Ken Lin	2020/07/13	MICRO USB B/F SMD 4DIP
PIN 3	D+		CHECKED BY:	DATE :	PART NO.
PIN 4	ID		Janice Liu	2020/07/13	MUSB05-01-357
PIN 5	GND		APPROVED BY1:	DATE :	MOLD NO.
		Richard Hsieh	2020/07/13	NA	
		APPROVED BY2:	DATE :	DRAW NO.	
		Richard Hsieh	2020/07/13	SHEET NO.	1 OF 1